

**What is claimed is:**

**[Claim 1]** 1. An electrical package structure, incorporating a chip with polymer thereon and comprising at least:

a package, comprising:

a carrier;

a chip having an active surface, disposed on the carrier; and

a plurality of wires electrically connecting the chip and the carrier;

a polymer, disposed at periphery of the active surface of the chip extending to sidewalls of the chip; and

a molding compound covering the chip, the wires and the polymer.

**[Claim 2]** 2. The electrical package structure of claim 1, wherein the polymer further covers a portion of each wire near the active surface of the chip.

**[Claim 3]** 3. The electrical package structure of claim 1, wherein the polymer further covers a portion of the carrier.

**[Claim 4]** 4. The electrical package structure of claim 1, wherein the polymer is shaped as a ring covering whole periphery of the active surface of the chip.

**[Claim 5]** 5. The electrical package structure of claim 1, wherein the polymer is shaped as strips covering two opposite edges of the active surface of the chip.

**[Claim 6]** 6. The electrical package structure of claim 1, wherein the polymer is shaped as a plurality of pieces covering four corners of the active surface of the chip.

**[Claim 7]** 7. The electrical package structure of claim 1, wherein the carrier comprises a leadframe or a circuit substrate.

**[Claim 8]** 8. The electrical package structure of claim 1, wherein the polymer comprises a stress buffer polymer.

**[Claim 9]** 9. The electrical package structure of claim 8, wherein the stress buffer polymer comprises epoxy resin or polyimide.

**[Claim 10]** 10. An electrical package structure, incorporating a chip with polymer thereon and comprising at least:

a package, comprising:

a carrier;

a plurality of chips each having an active surface, stacked on the carrier; and

a plurality of wires electrically connecting the chips and the carrier;

a polymer, disposed at periphery of the active surface of each chip extending to sidewalls of the chip; and

a molding compound covering the chips, the wires and the polymer.

**[Claim 11]** 11. The electrical package structure of claim 10, wherein the polymer on a chip further covers a portion of each wire near the active surface of the chip.

**[Claim 12]** 12. The electrical package structure of claim 10, wherein the polymer further covers a portion of the carrier.

**[Claim 13]** 13. The electrical package structure of claim 10, wherein the chip nearest to the carrier is bonded to the carrier through flip-chip bonding, and the other chips are bonded to the carrier through wire bonding.

**[Claim 14]** 14. The electrical package structure of claim 13, wherein the chips are also coupled with each other through wire bonding.

**[Claim 15]** 15. The electrical package structure of claim 10, wherein the chips are all bonded to the carrier through wire bonding.

**[Claim 16]** 16. The electrical package structure of claim 15, wherein the chips are also coupled with each other through wire bonding.

**[Claim 17]** 17. The electrical package structure of claim 10, further comprising at least one spacer disposed between the chips.

**[Claim 18]** 18. The electrical package structure of claim 17, wherein the spacer comprises a dummy chip.

[Claim 19] 19. The electrical package structure of claim 10, wherein the polymer on a chip is shaped as a ring covering whole periphery of the active surface of the chip.

[Claim 20] 20. The electrical package structure of claim 10, wherein the polymer on a chip is shaped as strips covering two opposite edges of the active surface of the chip.

[Claim 21] 21. The electrical package structure of claim 10, wherein the polymer on a chip is shaped as a plurality of pieces covering four corners of the active surface of the chip.

[Claim 22] 22. The electrical package structure of claim 10, wherein the carrier comprises a leadframe or a circuit substrate.

[Claim 23] 23. The electrical package structure of claim 10, wherein the polymer comprises a stress buffer polymer.

[Claim 24] 24. The electrical package structure of claim 23, wherein the stress buffer polymer comprises epoxy resin or polyimide.

[Claim 25] 25. A chip with polymer thereon, comprising at least:

a chip having an active surface; and

a polymer, disposed at periphery of the active surface of the chip extending to sidewalls of the chip.

[Claim 26] 26. The chip with polymer thereon of claim 25, further comprising a plurality of wires electrically connecting the chip and a carrier for carrying the chip.

[Claim 27] 27. The chip with polymer thereon of claim 26, wherein the polymer further covers a portion of each wire near the active surface of the chip.

[Claim 28] 28. The chip with polymer thereon of claim 26, wherein the polymer further covers a portion of the carrier.

[Claim 29] 29. The chip with polymer thereon of claim 26, wherein the carrier comprises a leadframe or a circuit substrate.

[Claim 30] 30. The electrical package structure of claim 25, wherein the polymer is shaped as a ring covering whole periphery of the active surface of the chip.

[Claim 31] 31. The electrical package structure of claim 25, wherein the polymer is shaped as strips covering two opposite edges of the active surface of the chip.

[Claim 32] 32. The electrical package structure of claim 25, wherein the polymer is shaped as a plurality of pieces covering four corners of the active surface of the chip.

[Claim 33] 33. The electrical package structure of claim 25, wherein the polymer comprises a stress buffer polymer.

[Claim 34] 34. The electrical package structure of claim 33, wherein the stress buffer polymer comprises epoxy resin or polyimide.